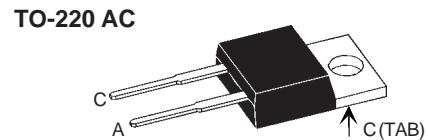
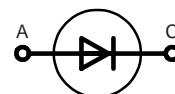


HiPerFRED™ Epitaxial Diode with soft recovery

I_{FAV} = 10 A
V_{RRM} = 300 V
t_{rr} = 30 ns

V _{RSM} V	V _{RRM} V	Type
300	300	DSEP 8-03A



A = Anode, C = Cathode, TAB = Cathode

Symbol	Conditions	Maximum Ratings	
I _{FRMS}		35	A
I _{FAVM}	T _C = 130°C; rectangular, d = 0.5	10	A
I _{FSM}	T _{VJ} = 45°C; t _p = 10 ms (50 Hz), sine	60	A
E _{AS}	T _{VJ} = 25°C; non-repetitive I _{AS} = 2 A; L = 180 µH	0.5	mJ
I _{AR}	V _A = 1.5·V _R typ.; f = 10 kHz; repetitive	0.2	A
T _{VJ}		-55...+175	°C
T _{VJM}		175	°C
T _{stg}		-55...+150	°C
P _{tot}	T _C = 25°C	60	W
M _d	mounting torque	0.4...0.6	Nm
Weight	typical	2	g

- Features**
- International standard package
 - Planar passivated chips
 - Very short recovery time
 - Extremely low switching losses
 - Low I_{RM}-values
 - Soft recovery behaviour
 - Epoxy meets UL 94V-0

Applications

- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode in converters and motor control circuits
- Rectifiers in switch mode power supplies (SMPS)
- Inductive heating
- Uninterruptible power supplies (UPS)
- Ultrasonic cleaners and welders

Advantages

- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low I_{RM} reduces:
 - Power dissipation within the diode
 - Turn-on loss in the commuting switch

Dimensions see Outlines.pdf

Symbol	Conditions	Characteristic Values	
		typ.	max.
I _R ①	T _{VJ} = 25°C V _R = V _{RRM} T _{VJ} = 150°C V _R = V _{RRM}	60 0.25	µA mA
V _F ②	I _F = 10 A; T _{VJ} = 150°C T _{VJ} = 25°C	1.29 1.75	V
R _{thJC} R _{thCH}		0.5	K/W K/W
t _{rr}	I _F = 1 A; -di/dt = 50 A/µs; V _R = 30 V; T _{VJ} = 25°C	30	ns
I _{RM}	V _R = 100 V; I _F = 12 A; -di _F /dt = 100 A/µs T _{VJ} = 100°C	2.4	A

Recommended replacement:
DPG10I300PA

Pulse test: ① Pulse Width = 5 ms, Duty Cycle < 2.0 %
② Pulse Width = 300 µs, Duty Cycle < 2.0 %

Data according to IEC 60747 and per diode unless otherwise specified

IXYS reserves the right to change limits, test conditions and dimensions.

20080317a

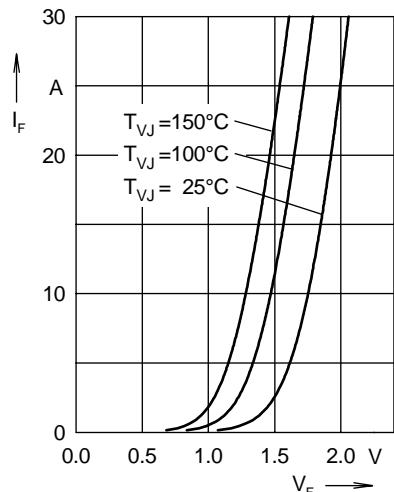
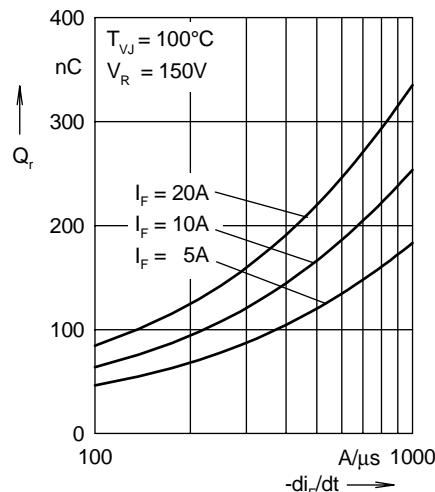
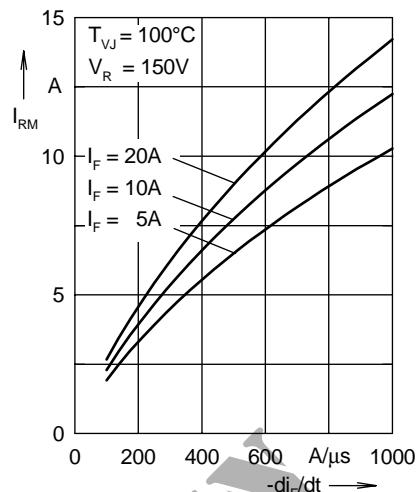
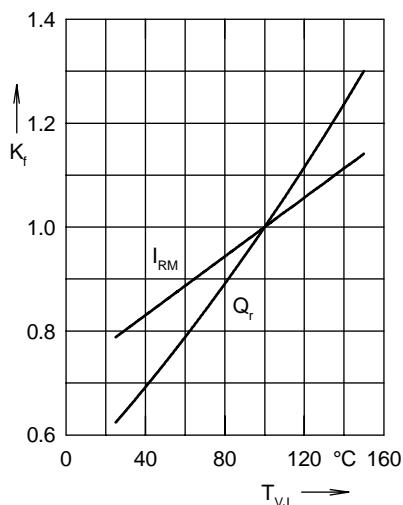
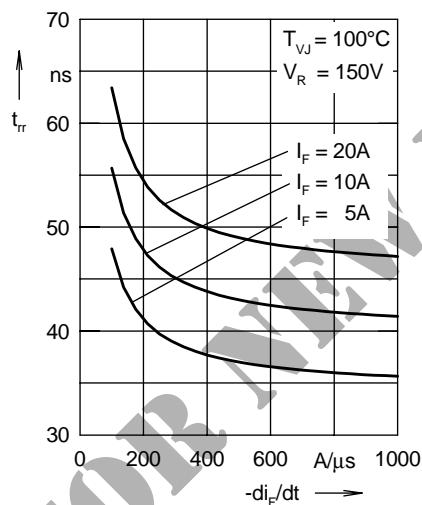
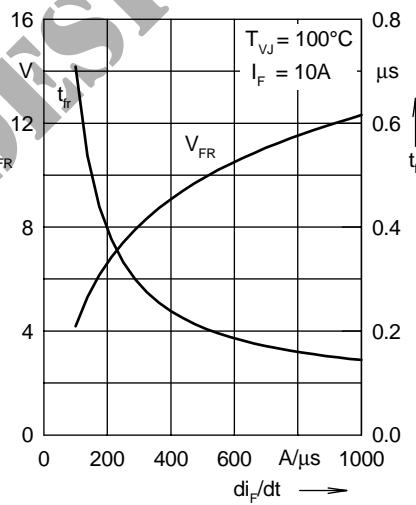
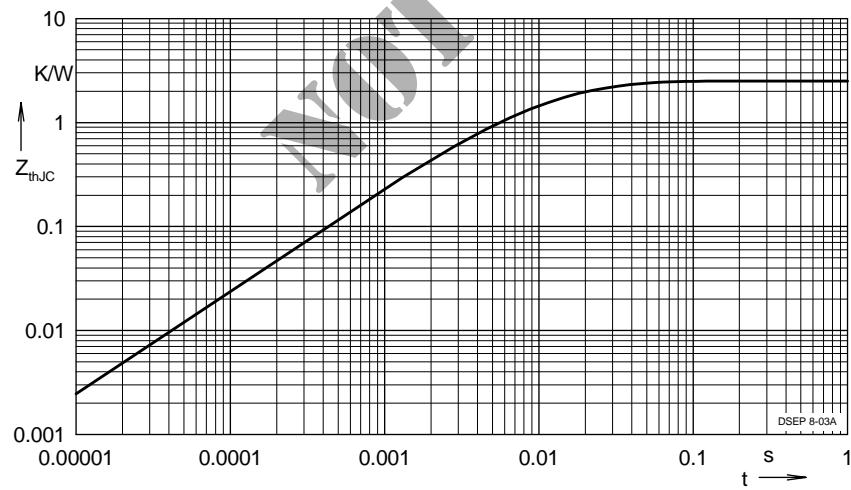
Fig. 1 Forward current I_F versus V_F Fig. 2 Reverse recovery charge Q_r versus $-di_F/dt$ Fig. 3 Peak reverse current I_{RM} versus $-di_F/dt$ Fig. 4 Dynamic parameters Q_r , I_{RM} versus T_{VJ} Fig. 5 Recovery time t_{rr} versus $-di_F/dt$ Fig. 6 Peak forward voltage V_{FR} and t_{fr} versus di_F/dt 

Fig. 7 Transient thermal resistance junction to case

NOTE: Fig. 2 to Fig. 6 shows typical values

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	1.449	0.005
2	0.558	0.0003
3	0.493	0.017